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Vishay Siliconix

Automotive N-Channel 40 V (D-S) 175 °C MOSFET

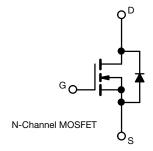


PRODUCT SUMMARY				
V _{DS} (V)	40			
$R_{DS(on)}(\Omega)$ at $V_{GS} = 10 \text{ V}$	0.0025			
I _D (A)	243			
Configuration	Single			

FEATURES

- TrenchFET® Gen IV power MOSFET
- AEC-Q101 qualified
- 100 % Rq and UIS tested
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912





ORDERING INFORMATION	
Package	PowerPAK® SO-8L
Lead (Pb)-free and halogen-free	SQJ154EP (for detailed order number please see www.vishay.com/doc?79776)

ABSOLUTE MAXIMUM RATINGS (T	SYMBOL	LIMIT	UNIT		
Drain-source voltage	V _{DS}	40	.,		
Gate-source voltage		V _{GS}	± 20	V	
Continuous dusin summent	T _C = 25 °C		243		
Continuous drain current	T _C = 125 °C	I _D	140		
Continuous source current (diode conduction)		I _S	194	Α	
Pulsed drain current ^a		I _{DM}	970		
Single pulse avalanche current		I _{AS}	33		
Single pulse avalanche energy L = 0.1 mH		E _{AS}	54	mJ	
Maximum nauca dissination 8	T _C = 25 °C	Р	214	W	
Maximum power dissipation ^a	T _C = 125 °C	P_{D}	71		
Operating junction and storage temperature range		T _J , T _{stg}	-55 to +175	°C	
Soldering recommendations (peak temperature) c		-	260	30	

THERMAL RESISTANCE RATINGS				
PARAMETER		SYMBOL	LIMIT	UNIT
Junction-to-ambient F	PCB mount b	R_{thJA}	68	°C/W
Junction-to-case (drain)		R_{thJC}	0.7	C/VV

Notes

- a. Pulse test; pulse width \leq 300 µs, duty cycle \leq 2 %
- b. When mounted on 1" square PCB (FR4 material)
- c. See solder profile (www.vishay.com/doc?73257). The end of the lead terminal is exposed copper (not plated) as a result of the singulation process in manufacturing. A solder fillet at the exposed copper tip cannot be guaranteed and is not required to ensure adequate bottom side solder interconnection



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PARAMETER	SYMBOL	TES	T CONDITIONS	MIN.	TYP.	MAX.	UNIT	
Static							•	
Drain-source breakdown voltage	V _{DS}	$V_{GS} = 0$, $I_D = 250 \mu A$		40	-	-	V	
Gate-source threshold voltage	V _{GS(th)}	V _{DS} =	= V _{GS} , I _D = 250 μA	2.5	3.0	3.5	V	
Gate-source leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$		-	-	± 100	nA	
		$V_{GS} = 0 V$	V _{DS} = 40 V	-	-	1		
Zero gate voltage drain current	I _{DSS}	V _{GS} = 0 V	V _{DS} = 40 V, T _J = 125 °C	-	-	50	μΑ	
		$V_{GS} = 0 V$	V _{DS} = 40 V, T _J = 175 °C	-	-	250		
On-state drain current ^a	I _{D(on)}	V _{GS} = 10 V	$V_{DS} \ge 5 \text{ V}$	30	-	-	Α	
		V _{GS} = 10 V	I _D = 15 A	-	0.0022	0.0025		
Drain-source on-state resistance a	R _{DS(on)}	V _{GS} = 10 V	I _D = 15 A, T _J = 125 °C	-	-	0.0038	Ω	
		V _{GS} = 10 V	I _D = 15 A, T _J = 175 °C	-	-	0.0045		
Forward transconductance b	9 _{fs}	V _{DS}	V _{DS} = 15 V, I _D = 10 A		48	-	S	
Dynamic ^b								
Input capacitance	C _{iss}			-	2585	3620		
Output capacitance	C _{oss}	$V_{GS} = 0 V$	$V_{DS} = 25 \text{ V}, f = 1 \text{ MHz}$	-	830	1162	pF	
Reverse transfer capacitance	C _{rss}			-	62	87		
Total gate charge ^c	Qg			-	43	65		
Gate-source charge c	Q_{gs}	$V_{GS} = 10 \text{ V}$	$V_{DS} = 40 \text{ V}, I_{D} = 50 \text{ A}$	-	11	-	nC	
Gate-drain charge c	Q_{gd}			-	12	-		
Gate resistance	Rg		f = 1 MHz	-	3.7	5.7	Ω	
Turn-on delay time ^c	t _{d(on)}			-	13	20		
Rise time ^c	t _r	V_{DD}	= 20 V, $R_L = 2 \Omega$	-	3	5		
Turn-off delay time ^c	t _{d(off)}	$I_D \cong 10 \text{ A},$	$V_{GEN} = 10 \text{ V}, R_g = 1 \Omega$	-	22	33	ns	
Fall time ^c	t _f			-	5	8		
Source-Drain Diode Ratings and Chara	acteristics ^b							
Pulsed current ^a	I _{SM}			-		970	Α	
Forward voltage	V _{SD}	I _F = 15 A, V _{GS} = 0 V		-	-	1.1	V	
Body diode reverse recovery time	t _{rr}			-	36	72	ns	
Body diode reverse recovery charge	Q _{rr}] . 40	Λ di/dt = 100 Λ/μο	-	25	50	nC	
Reverse recovery fall time	t _a	I _F = 10 A, di/dt = 100 A/μs		-	18	-		
Reverse recovery rise time	t _b	7		-	19	-	ns	
Body diode peak reverse recovery current	I _{RM(REC)}			-	1.3	-	А	

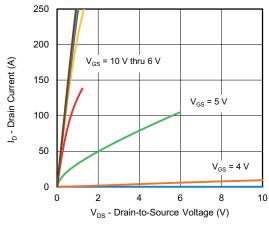
Notes

- a. Pulse test; pulse width $\leq 300~\mu s,$ duty cycle $\leq 2~\%$
- b. Guaranteed by design, not subject to production testing
- c. Independent of operating temperature

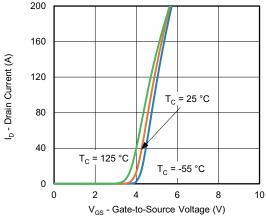
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



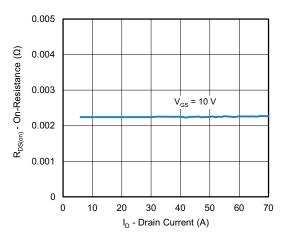
TYPICAL CHARACTERISTICS (T_A = 25 °C, unless otherwise noted)



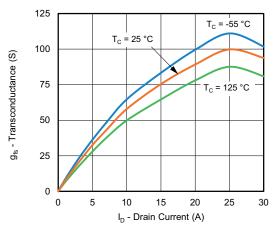
Output Characteristics



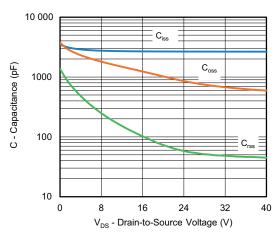
Transfer Characteristics



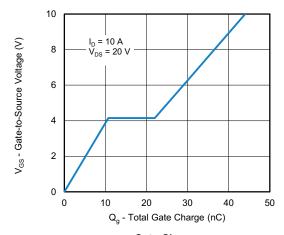
On-Resistance vs. Drain Current



Transconductance



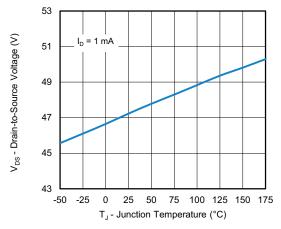
Capacitance



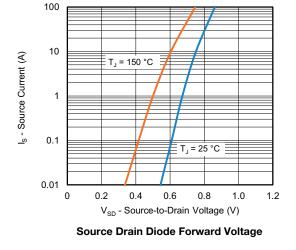
Gate Charge

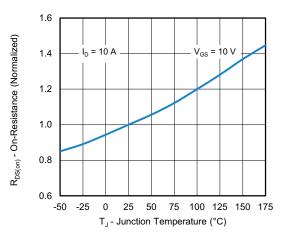


TYPICAL CHARACTERISTICS (T_A = 25 °C, unless otherwise noted)

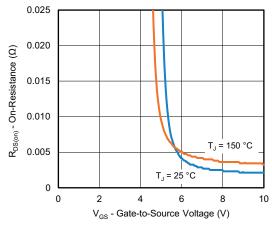


Drain Source Breakdown vs. Junction Temperature

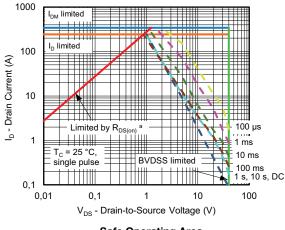




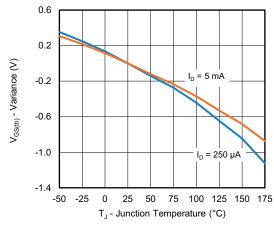
On-Resistance vs. Junction Temperature



On-Resistance vs. Gate-to Source Voltage



Safe Operating Area



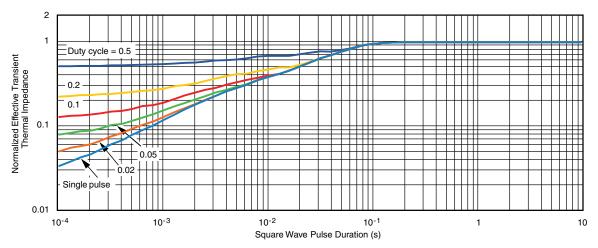
Variance vs. Junction Temperature

Note

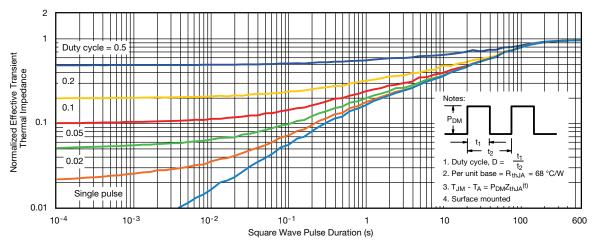
a. V_{GS} > minimum V_{GS} at which $R_{DS(on)}$ is specified



TYPICAL CHARACTERISTICS (T_A = 25 °C, unless otherwise noted)



Normalized Thermal Transient Impedance, Junction-to-Case



Normalized Thermal Transient Impedance, Junction-to-Ambient

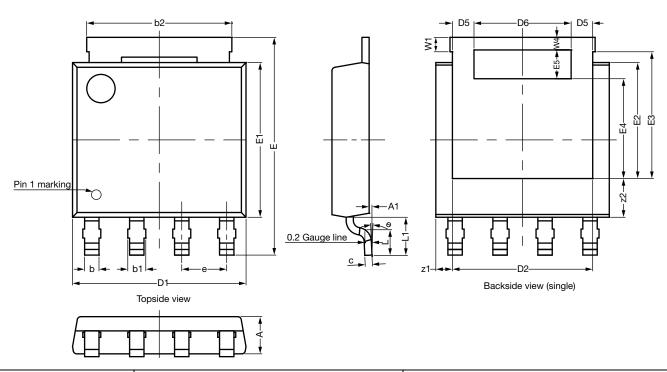
Note

- The characteristics shown in the two graphs
 - Normalized Transient Thermal Impedance Junction-to-Ambient (25 °C)
 - Normalized Transient Thermal Impedance Junction-to-Case (25 °C) are given for general guidelines only to enable the user to get a "ball park" indication of part capabilities. The data are extracted from single pulse transient thermal impedance characteristics which are developed from empirical measurements. The latter is valid for the part mounted on printed circuit board FR4, size 1" x 1" x 0.062", double sided with 2 oz. copper, 100 % on both sides. The part capabilities can widely vary depending on actual application parameters and operating conditions

Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package / tape drawings, part marking, and reliability data, see www.vishay.com/ppg?77466



PowerPAK® SO-8L (PPKSO8LWLA) Case Outline 3



DIM.		MILLIMETERS		INCHES			
DIIVI.	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.	
Α	1.00	1.05	1.10	0.039	0.041	0.043	
A1	0.00		0.127	0.000		0.005	
b	0.33	0.41	0.49	0.013	0.016	0.019	
b1	0.43	0.51	0.59	0.017	0.020	0.023	
b2	4.00	4.10	4.20	0.157	0.161	0.165	
С	0.15	0.20	0.25	0.006	0.008	0.010	
D1	4.80	4.90	5.00	0.189	0.193	0.197	
D2	3.86	3.96	4.06	0.152	0.156	0.160	
D5	0.51	0.61	0.71	0.020	0.024	0.028	
D6	2.64	2.74	2.84	0.104	0.108	0.112	
е		1.27 BSC		0.050 BSC			
E	6.05	6.15	6.25	0.238	0.242	0.246	
E1	4.27	4.37	4.47	0.168	0.172	0.176	
E2	3.18	3.28	3.38	0.125	0.129	0.133	
E3	3.48	3.58	3.68	0.137	0.141	0.145	
E4	2.72	2.82	2.92	0.107	0.111	0.115	
E5	0.71	0.81	0.91	0.028	0.032	0.036	
L	0.62	0.72	0.82	0.024	0.028	0.032	
L1	0.92	1.07	1.22	0.036	0.042	0.048	
W1	0.31	0.41	0.51	0.012	0.016	0.020	
W4	0.31	0.36	0.41	0.012	0.014	0.016	
z1	0.37	0.47	0.57	0.015	0.019	0.022	
z2	0.99	1.09	1.19	0.039	0.043	0.047	
θ	0°		5°	0°		5°	

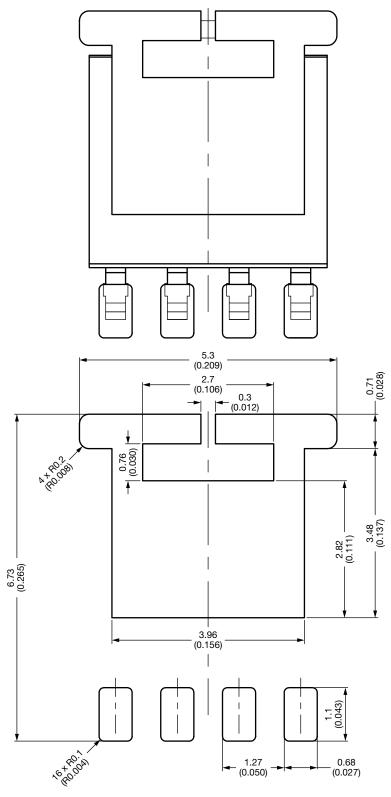
Note

• Millimeter will govern

Revison: 18-Sep-2023 1 Document Number: 76666



Recommended Land Pattern PowerPAK® SO-8L Single Short Ear



Dimensions in Millimeters (Inches)



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